

HGPA12 High Thermal Conductivity Gap Pad

BENEFITS AND FEATURES

- 12.0W/m·K thermal conductivity
- For automation
- Low residual stress for pressure sensitive devices
- Low oil bleeding & Low volatile (D3-D10<100ppm)

OVERVIEW

Honeywell HGPA12 is designed for automation assembly. Due to its special formulation design, it provides not only 12.0W/m·K high thermal but also good mechanical properties.

that is helpful to reduce its residual stress and benefits pressure sensitive devices a

lot. HGPA12 is low volatile and low oil bleeding grade, and it can be used in various applications, which is sensitive to oil leakage.

TYPICAL APPLICATIONS

- Telecommunications
- GPU & data center
- High power lighting applications
- Wireless devices

STORAGE & USE

Shelf Life: 12 months at 0-35°C

Temperature range for usage: -40°C~125°C

Property	HGPA12	Test Method
Color	Grayish green	By visual
Thickness range (mm)	0.5-5.0	N/A
Thermal Conductivity (W/m·K)	12.0	ASTM D5470
Thermal Impedance (in ² ·K/W)(1mm@10psi)	0.14	ASTM D5470
Specific gravity	3.3	ASTM D792
Hardness (Shore 00)	45	ASTM D2240
Volatile content (TML%)	0.11	ASTM E595
Volatile content (CVCm%)	0.03	ASTM E595
Dielectric constant @1MHz	5.7	ASTM D150
Volume resistivity (Ohm.cm)	≥1.0x10 ¹³	ASTM D257
Flame retardancy	V-0	UL 94 equivalent
Temperature range	-40 ~ 125°C	N/A

*Typical property data values should not be used as specifications

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